IN THE CLAIMS:

Please cancel Claims 1-9.

Please add new Claims 10-15:

- 1-9. (Cancelled)
- 10. (New) A method comprising polishing a composite material containing silica and silicon nitride with an acidic polishing slurry comprising:
 - (a) from about 0.1 to about 5%, by weight, of a colloidal silica abrasive,
 - (b) from about 0.5 to about 10%, by weight, of a fluoride salt

wherein the colloidal silica abrasive is present in a quantity ranging from about 0.1 to about 3.5% by weight and the fluoride salt is present in a quantity of from about 1 to about 6%, by weight, and

- (c) wherein the slurry has a pH ranging from about 2 to about 6.
- (New) The polishing slurry according to Claim 10, wherein the fluoride salt is an emmonium salt.
 - 12. (New) The polishing slurry according to Claim 10, wherein the fluoride salt is ammonium fluoride or ammonium hydrogen fluoride.
- 13. (New) The polishing slurry according to Claim 10, wherein the fluoride salt is ammonium hydrogen fluoride.
- 14. (New) The polishing slurry according to Claim 10, wherein the colloidal silica has a mean particle size of from about 10 nm to about 1 µm.
- 15. (New) The polishing slurry according to Claim 14, wherein the colloidal silica has a mean particle size of from about 20 nm to about 100 nm.